Reliability Report

Isahaya Electronics Corporation
Quality Assurance Department

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1. Reliability Test Results

Group	Test Items	Test Conditions	Test Quantity	Failure Quantity	Remarks
1	Solderability	Solder Temperature 230℃ Immersion Time 5sec Using rosin-type flux	45	0	
2	Resistance to solder heat	Solder Temperature 260℃ Immersion Time 10sec Immersing whole device	22	0	
3	Temperature Cycle	Ta=Tstg(min)～Tstg(max) 30min each cycle 100 cycles	45	0	
4	Humidity Resistance	Ta=85℃, 85%R.H. 1000hr	45	0	
5	Temperature Humidity Bias	Ta=85℃, 85%R.H. VKA=2.5V, IK=95mA 1000hr	45	0	
6	High Temperature Bias	Ta=85℃ VKA=2.5V, IK=95mA 1000hr	45	0	
7	High Temperature Storage	Ta=Tstg(max) 1000hr	45	0	
8	Low Temperature Storage	Ta=Tstg(min) 1000hr	45	0	
9	Pressure Cooker Test	121℃, 100%RH, 2×10^5Pa 96hr	45	0	
10	Electrostatic Breakdown Resistance	C=200pF, 0Ω Reference: GND pin Applied Voltage ±150V Applied once on each pin	11	0	
		C=100pF, 1.5kΩ Reference: GND pin Applied Voltage ±1000V Applied once on each pin	11	0	

2. Failure Criteria

Group	Failure Criteria
1	Less than 95% of the immersed part is covered with solder.
2～10	Which does not meet the electrical characteristics. Whose change rate exceeds ±20%. An apparent change in appearance is observed.

Measurement conditions are based on the corresponding specification sheet.
For further information of the contents above, please contact our Business Department.